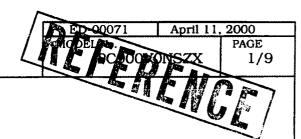
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K. Kusuda apr 12,2000	GROUP SHARP CORPOR	NAT		
A. Australian 19	SPECIFICATIO	OPTO-ELE	CCTRONIC DEVICES DI	
DEVI	CE SPECIFICATION FOR			
	PHOTOCOUPLER			
MODI	EL No. PC900V			
	(Business dealing name: PC9	OOVONSZYO		
	(Business dealing fiame: PCs	OUV OINSZA)		
		····		
	nclude materials protected under cop cause anyone to reproduce them with		tion ("Sharp").	
1	lease observe the absolute maximum	-	tions for use outlined	
in these specification sheets	s, as well as the precautions mentior	ned below. Sharp assum	es no responsibility	
	om use of the product which does no ed in these specification sheets, and			
(Precautions)	•	•		
•	signed for use in the following applic	eation areas;		
1 1 1	· Audio visual equipment · Home	1		
	ation equipment (Terminal) · Measones · Computers	uring equipment		
· • • · · · · · · · · · · · · · · · · ·	product in the above application area	ے is is for equipment listed	in paragraphs	
	be sure to observe the precautions gi			
	ares, such as fail-safe design and red			
and safety when the	f the overall system and equipment, als product is used for equipment wh			
	and precision, such as ;	. C	, ,	
	control and safety equipment (aircra Gas leakage sensor breakers I			
· Other safety eq				
	this product for equipment which re	quire extremely high reli	ability	
	ion and precision, such as ;	t (for trunk lines)		
Space equipment				
(4) Please contact and consult with a Sharp sales representative if there are any questions				
	ation of the above three paragraphs.			
3. Please contact and consult w	vith a Sharp sales representative for			
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	BY	(/ () Am	anaba	
D. 100		K. Hachimura,	,	
DATE		Department Genera Engineering Dept.,I		
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BY		ELECOM Group SHARP CORPORAT	ION	



1. Application

This specification applies to the outline and characteristics of photocoupler Model No. PC900V.

2. Outline

Refer to the attached sheet, page 3.

3. Ratings and characteristics

Refer to the attached sheet, page 3 to 5.

4. Reliability

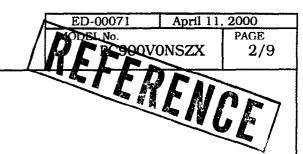
Refer to the attached sheet, page 8.

5. Outgoing inspection

Refer to the attached sheet, page 9.

- 6. Supplement
 - 6.1 Isolation voltage shall be measured in the following method.
 - (1) Short among pins 1 to 3 on the primary side and among pins 4 to 6 on the secondary side.
 - (2) The dielectric withstand tester with zero-cross circuit shall be used.
 - (3) The wave form of applied voltage shall be a sine wave.
 (It is recommended that the isolation voltage be measured in insulation oil.)
 - 6.2 The business dealing name used for this product when ordered or delivered shall be PC900V0NSZX.
 - 6.3 Package specifications

Refer to the attached sheets-2-1 to 2-3.



6.4 UL: Under preparation

6.5 Theory of operation

- (1) When the forward current of above the " $H \rightarrow L$ " threshold input current (I_{FHL}) is applied to the input side, the output will go "Low level".
- (2) When the forward current on the input side goes below the "L→H" threshold input current (I_{FLH}) is applied to the input side, the output will go "High level".
- 6.6 This product is not designed against irradiation.

This product is assembled with electrical input and output.

This product incorporates non-coherent light emitting diode.

6.7 ODS materials

This product shall not contain the following materials.

Also, the following materials shall not be used in the production process for this product.

Materials for ODS: CFC_S, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

6.8 Brominated flame retardants

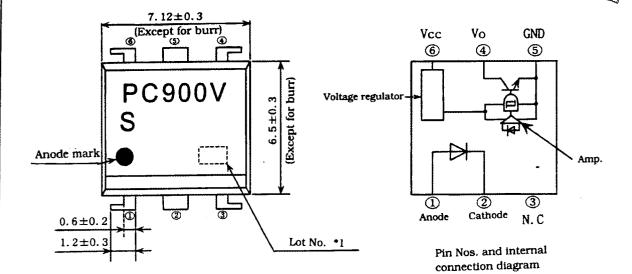
Specific brominated flame retardants such as the PBBO_S and PBB_S are not used in this device at all.

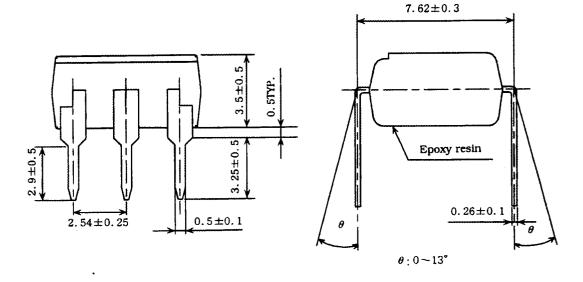
7. Notes

Refer to the attached sheet-1-1, 2.

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2. Outline





- *1) 2-digit number shall be marked according to DIN standard.
- *2) Marking is laser marking

Product mass: Approx. 0.36g

118	TIL	. 1	/1	mm
L L J I	111		. , į	1111111

PC900V

Name Outline Dimensions
(Business dealing name: PC900V0NSZX)

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- 3. Ratings and characteristics
 - 3.1 Absolute maximum ratings

Parameter		Symbol	Rating	Unit
	*1 Forward current	$I_{\mathbf{F}}$	50	mA
Innut	*2 Peak forward current	I _{FM}	1	Α
Input	Reverse voltage	V_R	6	v
	Power dissipation	Р	70	mW
	Supply voltage	Vec	16 -	v
Output	High level output voltage	V _{OH}	16	V
Output	Low level output current	I _{OL}	50	mA
	*1 Power dissipation	Ро	150	mW
*1 Total power dissipation		Ptot	170	mW
*3 Isolation voltage		Viso(rms)	5.0	kV
Operating temperature		Topr	-25 to +85	င
Storage temperature		Tstg	-40 to 125	Ω
*4 Soldering temperature		Tsol	260	Ĵ

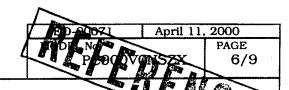
- *1 The derating factors of absolute maximum ratings due to ambient temperature are shown in Fig. 1, 2, 3.
- *2 Pulse width≤100 μ s, Dutyratio : 0.001
- *3 AC for 1 min, 40 to 60%RH
- *4 For 10 s

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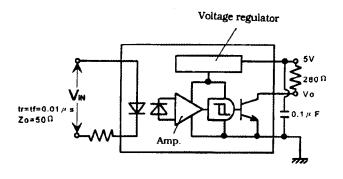
(Unspecified : Ta

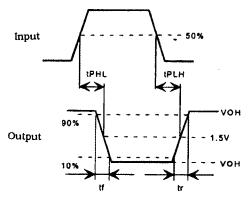
3.2 Electro-optical characteristics

		Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Conditions
	Forward voltage Reverse current Terminal capacitance		V _F	-	1.1	1.4	v	I _F =4mA
				0.7	1.0	·		I _F =0.3mA
lnpu			I_R	-	-	10	μΑ	Ta=25℃, V _R =3V
			Ct	-	30	250	pF	Ta=25°C, V=0 f=1kHz
		perating supply voltage ange	Vec	3	-	15	V	-
ıt l	L	ow level output voltage	V _{OL}	-	0.2	0.4	V	I _{OL} =16mA, Vcc=5V I _F =4mA
Output	F	ligh level output current	Г _{ОН}	-	+	100	μA	Vcc=Vo=15V I _F =0mA
	L	ow level supply current	f _{CCL}	-	2 .5	5.0	mA	Vcc=5V, I _F =4mA
	High level supply current		I _{CCH}	-	1.0	5.0	mA	Vcc=5V, I _F =0mA
	"H→L" threshold input current *1		I _{FHL}	,	1.1	2.0	mA	Ta=25°C, Vcc=5V R _L =280 Ω
	`	current i		-	-	4.0		Vec=5V, R_L =280 Ω
stics	"L→H" threshold input current *2		I _{FLH}	0.4	0.8	-	mA	Ta=25°C,Vcc=5V R _L =280 Ω
cteris				0.3	-	-		Vcc=5V, R_L =280 Ω
hara	Hysteresis *3		I _{FLH} /I _{FHL}	0.5	0.7	0.9	~	Vcc=5V, R _L =280Ω
ınsfer c	"L→H" threshold input current *2 Hysteresis *3 Isolation resistance		Riso	5×10 ¹⁰	1011	-	Ω	Ta=25°C, DC500V 40 to 60%RH
Tra	time	"H→L" propagation time	t _{PHL}	-	1	3		Ta=25℃
	nse t	"L→H" propagation time	t _{PLH}	-	2	6	μS	Vcc=5V, I _p =4mA
	Response	Fall time	tf	-	0.05	0.5	, ,	$R_1 = 280 \Omega$
	4 F	Rise time	tr	-	0.1	0.5		L ===================================



- *1 I_{FHL} represents forward current when output goes from "H" to "L".
- *2 $\, l_{FLH}$ represents forward current when output goes from "L" to "H".
- *3 Hysteresis : I_{FLH}/I_{FHL}
- *4 Test circuit for response time shall be shown below.

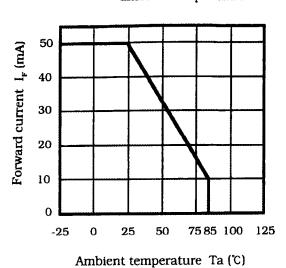




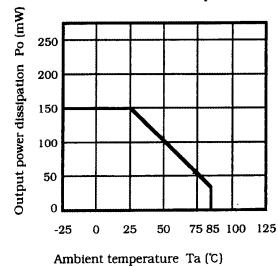
Test circuit diagram

Timing chart

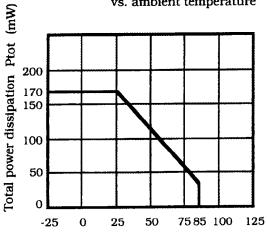
(Fig. 1) Forward current vs. ambient temperature



(Fig. 2) Output power dissipation vs. ambient temperature



(Fig. 3) Total power dissipation vs. ambient temperature



Ambient temperature Ta (℃)

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4. Reliability

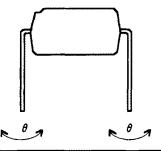
The reliability of products shall be satisfied with items listed below.

Confidence level: 90% LTPD: 10%/20%

Test Items	Test Conditions	Failure Judgement Criteria	Samples (n) Defective(C)
Solderability *2	230°C, 5 s		n=11, C=0
Soldering heat	260℃, 10 s	$V_F>U\times 1.2$	n=11, C=0
Terminal strength (Tension)	Weight : 5N 5 s/each terminal	I _R >U×2	n=11, C=0
Terminal strength (Bending) *3	Weight: 2.5N 2 times/each terminal	$V_{OL}>U\times1.2$ $I_{OH}>U\times1.2$	n=11, C=0
Mechanical shock	15 km/s 2 , 0.5ms 3 times/ \pm X, \pm Y, \pm Z direction	$I_{CCL}>U\times1.2$ $I_{CCH}>U\times1.2$	n=11, C=0
Variable frequency vibration	100 to 2000 to 100Hz/4min 200m/s ² 4 times/ X, Y, Z direction	I _{FHL} >U×1.3	n=11, C=0
Temperature cycling	1 cycle -40℃ to +125℃ (30min) (30min) 20 cycles test	$I_{\text{FLH}} < L \times 0.7$ $I_{\text{FLH}} / I_{\text{FHL}} \neq L \times 0.8$ $\sim U \times 1.2$	n=22,C=0
High temp. and high humidity storage	+85°C. 85%RH. 1000h	U : Upper specification	n=22,C=0
High temp. storage	+125°C, 1000h	limit	n=22,C=0
Low temp. storage	-40°C, 1000h	L : Lower specification	n=22,C=0
Operation life	I _F =10mA, Vcc=15V I _{OL} =16mA, Ta=25°C, 1000h	limit	n=22,C=0

^{*1} Test method, conforms to EIAJ ED 4701.

*3 Terminal bending direction is shown below.



^{*2} Solder shall adhere at the area of 95% or more of immersed portion of lead, and pin hole or other holes shall not be concentrated on one portion.

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- 5. Outgoing inspection
 - 5.1 Inspection items
 - (1) Electrical characteristics

 $\mathbf{V_F},\,\mathbf{I_R},\,\mathbf{V_{OL}},\,\mathbf{I_{OH}},\,\mathbf{I_{CCL}},\,\mathbf{I_{CCH}},\,\mathbf{I_{FHL}},\,\mathbf{I_{FLH}},\,\mathbf{Riso},\,\mathbf{Viso}$

- (2) Appearance
- 5.2 Sampling method and Inspection level

A single sampling plan, normal inspection level II based on ISO 2859 is applied. The AQL according to the inspection items are shown below.

Defect	Inspection item	AQL (%)
Major defect	Electrical characteristics Unreadable marking	0.065
Minor defect	Appearance defect except the above mentioned.	0.25

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PAGE
Attach
sheet-1-1

Precautions for Photocouplers

1 For cleaning

(1) Solvent cleaning: Solvent temperature 45°C or less

Immersion for 3 min or less

(2) Ultrasonic cleaning: The effect to device by ultrasonic cleaning differs

by cleaning bath size, ultrasonic power

output, cleaning time, PCB size or device mounting condition etc. Please test it in actual using condition and confirm that doesn't occur any defect before starting

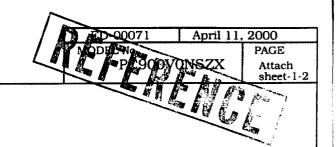
the ultrasonic cleaning.

(3) Applicable solvent: Ethyl alcohol, Methyl alcohol, Isopropyl alcohol

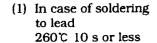
In case when the other solvent is used, there are cases that the packaging resin is eroded. Please use the other solvent after thorough confirmation is performed in actual using condition.

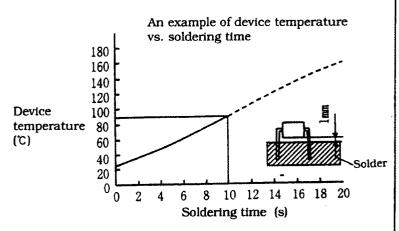
- 2. Please use the same as normal integration circuit about static electricity in order that this device is OPIC photocoupler.
- 3. In order to stabilize power supply line, we recommend to connect a by-pass capacitor of $0.01 \,\mu\text{F}$ or more between Vcc and GND near the device.
- 4. The detector which is used in this device, has parasitic diode between each pins and GND. There are cases that miss operation or destruction possibly may be occurred if electric potential of any pin becomes below GND level even for instant.

 Therefore it shall be recommended to design the circuit that electric potential of any pin does not become below GND level.
- 5. The LED used in the Photocoupler generally decreases the light emission power by operation. In case of long operation time, please design the circuit with considering the decreases of the light emission power of the LED. (50%/5years) Please decide the input current which become 2 times of MAX. I_{FHL}.



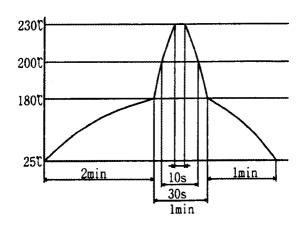
6. Precautions for Soldering Photocouplers





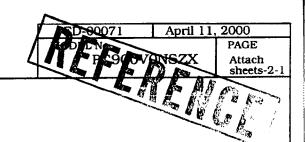
(2) If solder reflow:

It is recommended that only one soldering be done at the temperature and the time within the temperature profile as shown in the figure below.



(3) Other precautions

An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin. So keep the package temperature within that specified in Item (2). Also avoid immersing the resin part in the solder.



Package specification

1 Package materials

No.	Name	Materials	Purposes
1	Sleeve	Plastics with preventing static electricity	Products packaged
2	Stopper	Rubber	Products fixed
3	Packing case	Corrugated cardboard	Sleeve packaged
4	Kraft tape	Paper	Lid of packaged case fixed
5	Label	Paper	Model No., quantity, inspection date and lot No. specified

2 Package method

- (1) MAX. 50pcs. of products shall be packaged in a sleeve and both of sleeve edges shall be fixed by stoppers.
- (2) MAX. 20 sleeves above shall be packaged in a packing case and pack a sheet of cushion at one side.
- (3) Model No., quantity, inspection date and lot No. shall be marked on the label and this label shall be put on the side of the packaging case.
- (4) Case shall be closed with the lid and enclosed with kraft tape.

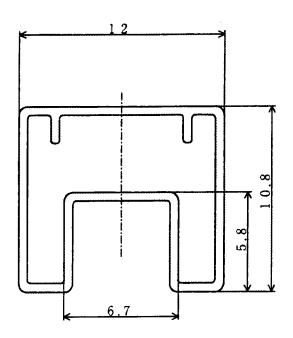
3 Package outline dimensions

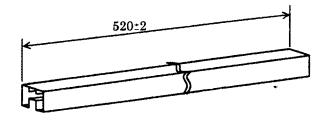
(1) Sleeve outline dimensions

Refer to the attached sheets-2-2.

(2) Packaging case outline dimensions

Refer to the attached sheets-2-3.





Length: L=520 \pm 2mm

Note 1) Thickness: 0.5±0.2mm

2) Outer R: 0.5mm

3) Process with applying antistatic agent.

4) Unless otherwise specified tolerances shall be ± 0.5 mm. (However except for deformation due to the rubber stopper in sleeve.)

Unit: 1/1mm

Name

Sleeve outline dimensions

